



Product Change Notification

CN-202404026F

Issue date: 27 Jun 2024
Effective date: 09 Oct 2024

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.



Release of 8 inch wafer diameter for PLVA Zener diodes

Change Category

☒		☐				☐	
Wafer		Assembl					
Fab		y					
Process		Process					
☒		☒	☐	Product Marking	☐	Test	☐
Wafer		☒	☐	Mechanical	☐	Location	Design
Fab		Assembl		Specification	☐	Test	Errata
Material		y			☐	Process	
s		Material	☐		☐	Test	Electrical
		s		Packing/Shipping/Labeli	☐	Equipme	spec./Te
☐		☐		ng	nt	st	coverage
Wafer		Assembl					
Fab		y					
Locatio		Location					
n							

Details of this change

Release of 8 inch wafer diameter for Zener diodes. Old products: Production using 6 inch wafer diameter Changed products: Production using 6 and 8 inch wafer diameter. Production on 8 inch wafer diameter

implies the use of the respective 8 inch wafer process technology.
The release of 8 inch wafer diameter is combined with a change in die size and the introduction of additional EMCs (epoxy mold compounds) GR646CHN and CV4112 in SOT23 package.
Please refer to the Self Qualification Report for details and list of affected product types.

CN-202404026F_changeMatrix.xlsx:
https://qcm.nexperia.com/Document/DOC-575931/CN-202404026F_changeMatrix.xlsx

SQR_CN_202404026F.pdf: https://qcm.nexperia.com/Document/DOC-575930/SQR_CN_202404026F.pdf

PCN-FORM-Rev_5_0_2_CN-202404026F.xlsm:
https://qcm.nexperia.com/Document/DOC-575527/PCN-FORM-Rev_5_0_2_CN-202404026F.xlsm

PCN-Delta-Qualification-Matrix-ZVEI-5_0_16_CN-202404026F.xlsm:
https://qcm.nexperia.com/Document/DOC-575526/PCN-Delta-Qualification-Matrix-ZVEI-5_0_16_CN-202404026F.xlsm

Why do we implement this change?

Capacity expansion in wafer fab - Next phase in 8 inch release after start with 8 inch implementation of bipolar transistors in 2011
Continued alignment with world technology trends on state of the art production tools for discrete components
Increase flexibility and volume ramp-up

Identification of affected products

The 8 inch products can be identified by a marker on the die surface.

Management summary

- #1 SEM-DE-03 - Die Shrink
- #2 SEM-PW-02 - New wafer diameter
- #3 SEM-PW-14 - Lithography
- #4 SEM-PA-11 - Mold compound

Product availability

Production

Planned first shipment: 14 Oct 2024

Existing inventory will be shipped until depleted

Sample information

Samples are available upon request

Impact

No impact to the product's functionality anticipated

Data sheet revision

No impact to existing datasheet

Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 27 Jul 2024. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Additional information

[View Change Notification Online](#)

Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

In case of distribution, please contact you distribution partner.

About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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